

Activities of the WP2.3 at UNIGE

Focus on REBCO coated conductors



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Outline

- **Results of the measurement campaign on REBCO coated conductors from various manufacturers**
 - Main characteristics of the examined tapes
 - Transport I_c measurements up to 2 kA in variable temperature and at various orientations
 - Magnetization measurements and pinning force analysis
- **A new experiment to test the delamination strength of REBCO coated conductors**
- **Summary and conclusions**






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What has been tested – Catalogue of the Tapes

	Width	REBCO Type	REBCO Thickness	Deposition Method	Pinning Type	Hastelloy Thickness	Cu Stabilizer	$I_c(77K, s.f.)$
	Q1/2019 4 mm	EuBCO	2.5 μm	IBAD/PLD	BHO columns (artificial)	50 μm	2 x 40 μm electroplated	n/a
	Q2/2023 2 mm						2 x 20 μm electroplated	380 A/cm 555 A/cm
	4 mm	YBCO	3.1 μm	IBAD/PLD	Y ₂ O ₃ particles (native)	▲ 100 μm	2 x 20 μm electroplated	550 A/cm
			2.7 μm			40 μm	2 x 5 μm electroplated	n/a
	3 mm	EuBCO	3 μm	IBAD/PLD	BHO columns (artificial)	▼ 30 μm	2 x 10 μm electroplated	▲ 590 A/cm
	Q1/2018 4 mm	GdBCO	3 μm	ISD/EB-PVD	Gd ₂ O ₃ particles (native)	100 μm	2 x 20 μm electroplated	517 A/cm
	Q4/2021				Gd ₂ O ₃ particles (native)	40 μm	2 x 10 μm PVD-plated	340 A/cm
	Q3/ 2023 6 mm				BHO particles (artificial)	50 μm		
	4 mm	undisclosed	▼ 1.5 μm	IBAD/MOCVD	BZO columns (artificial)	50 μm	2 x 5 μm Electroplated	▼ 148 A/cm






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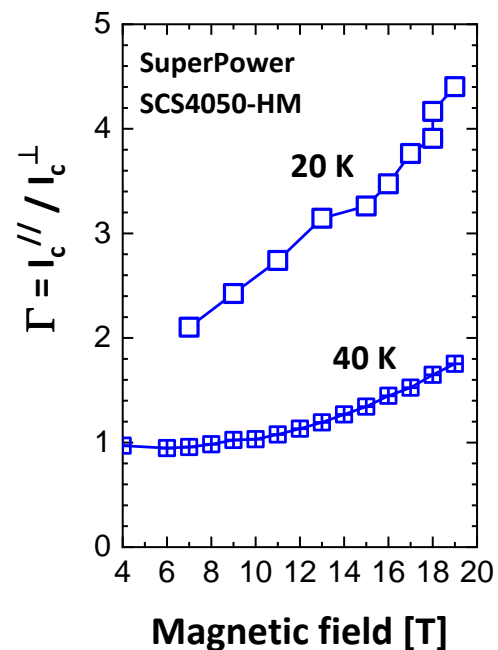
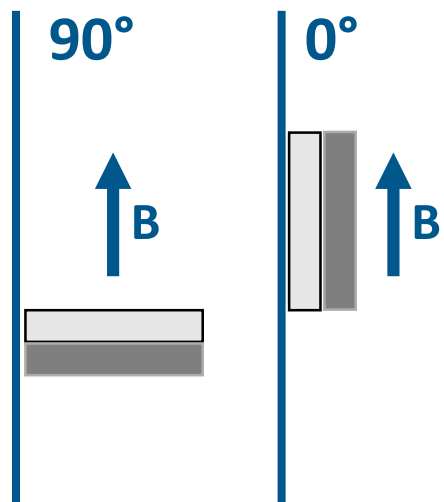
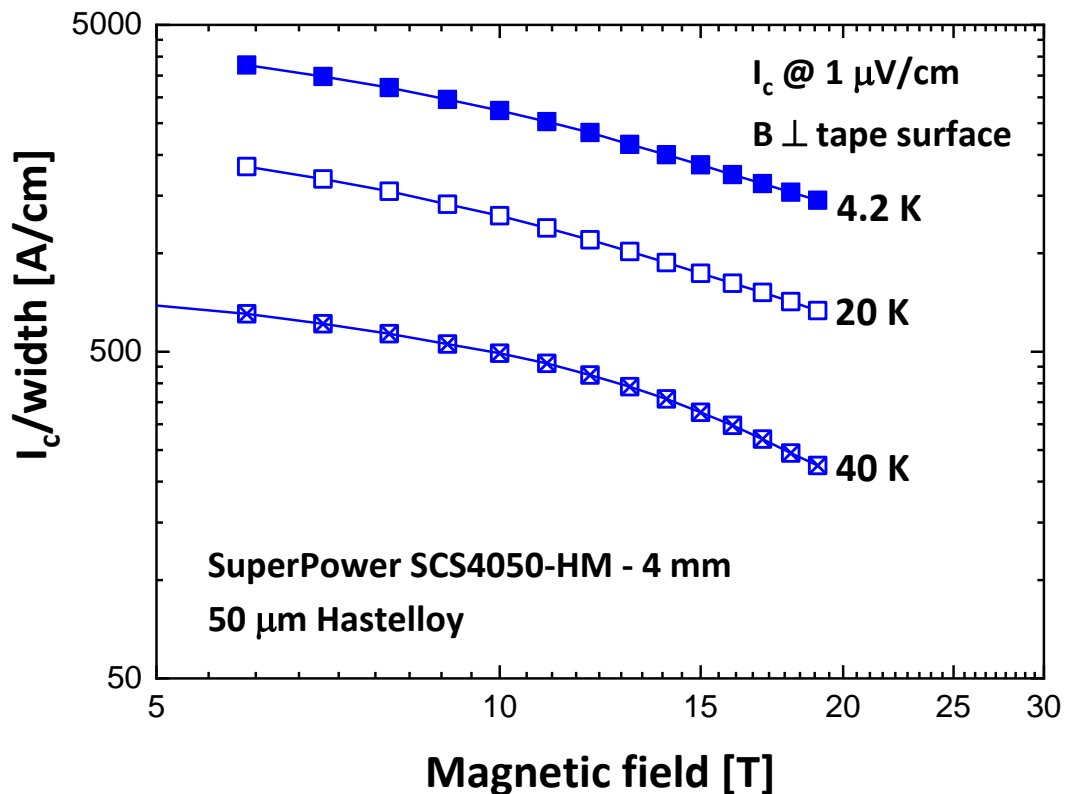
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Characterization protocol

- **Transport I_c at 4.2 K, 20 K and 40 K up to 19 T**
 - I_c at $\theta = 90^\circ$ and 0° wrt the tape surface + some intermediate angles
 - Currents up to 2 kA (4.2 K) or 1 kA (> 4.2 K) were the upper limits of the experiments
 - Measurements performed on full width tapes
- **Magnetization loops up to 77 K and 7 T**
- **Scaling analysis of the pinning force, from magnetization and transport data**

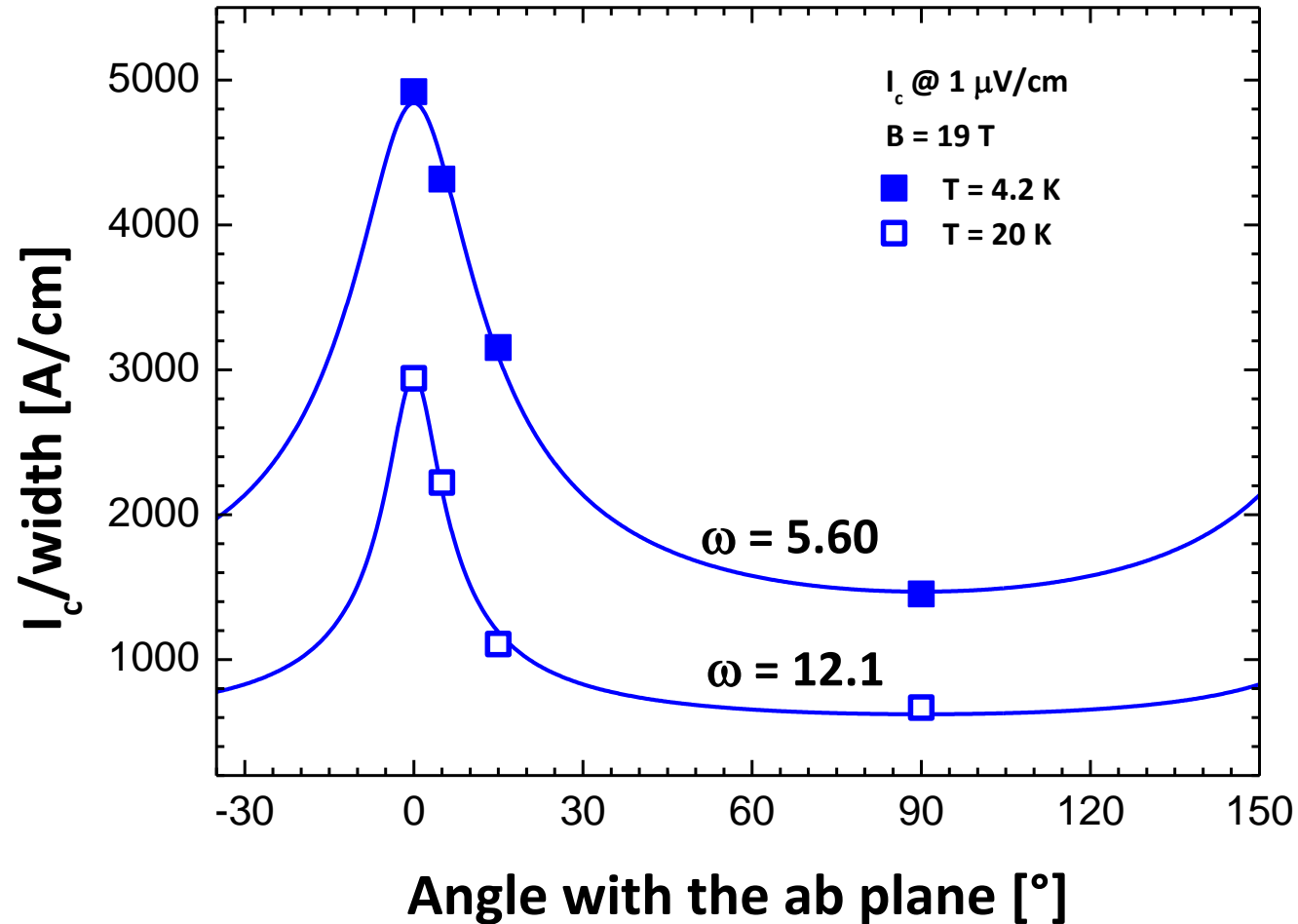
tapes: minimum and maximum I_c at 4.2 K and 20 K

Material received in Q1/2023



I_c /width (4.2K, 19T)	I_c /width (20K, 19T)	I_c /width (40K, 19T)
1450 A/cm	670 A/cm	220 A/cm

tapes: Angular dependence of I_c



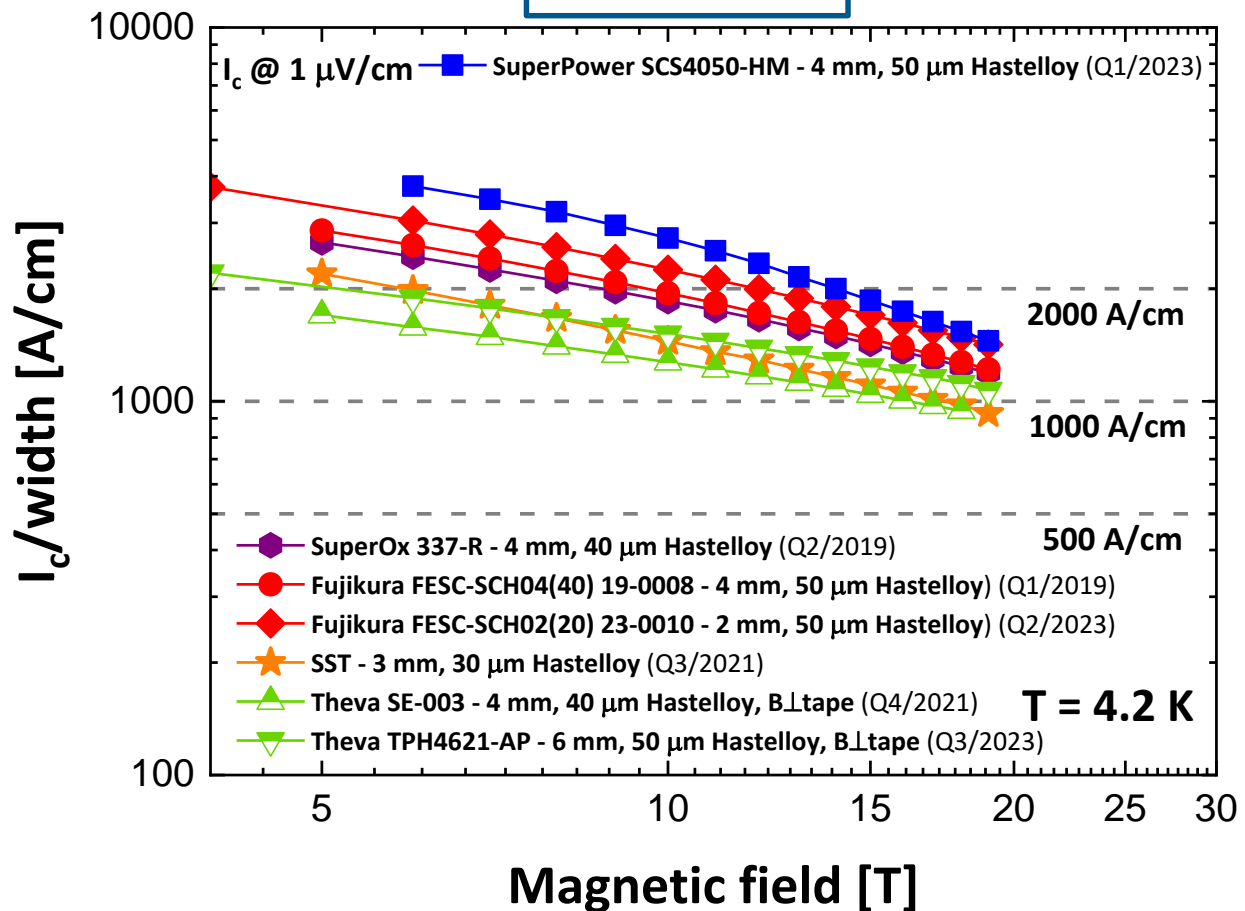
Fit performed according to the Hilton model

$$I_c(B, \theta) = I_c(B, 90^\circ) + [I_c(B, 0^\circ) - I_c(B, 90^\circ)] \frac{\omega f(\omega, \theta) - 1}{\omega - 1}$$

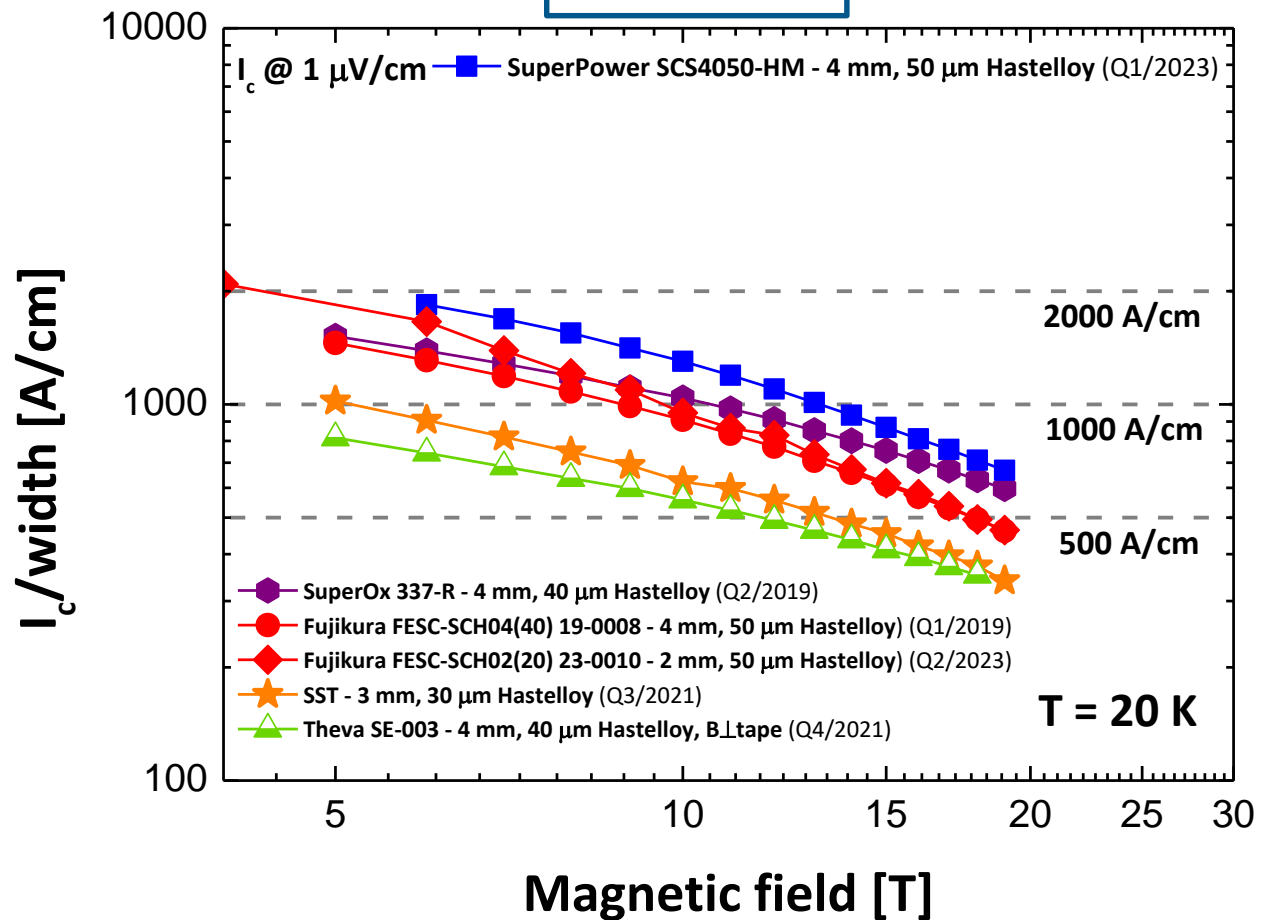
$$f(\omega, \theta) = [\omega^2 \sin^2 \theta + \cos^2 \theta]^{-\frac{1}{2}}$$

Comparison of the performance: I_c / width

T = 4.2 K



T = 20 K

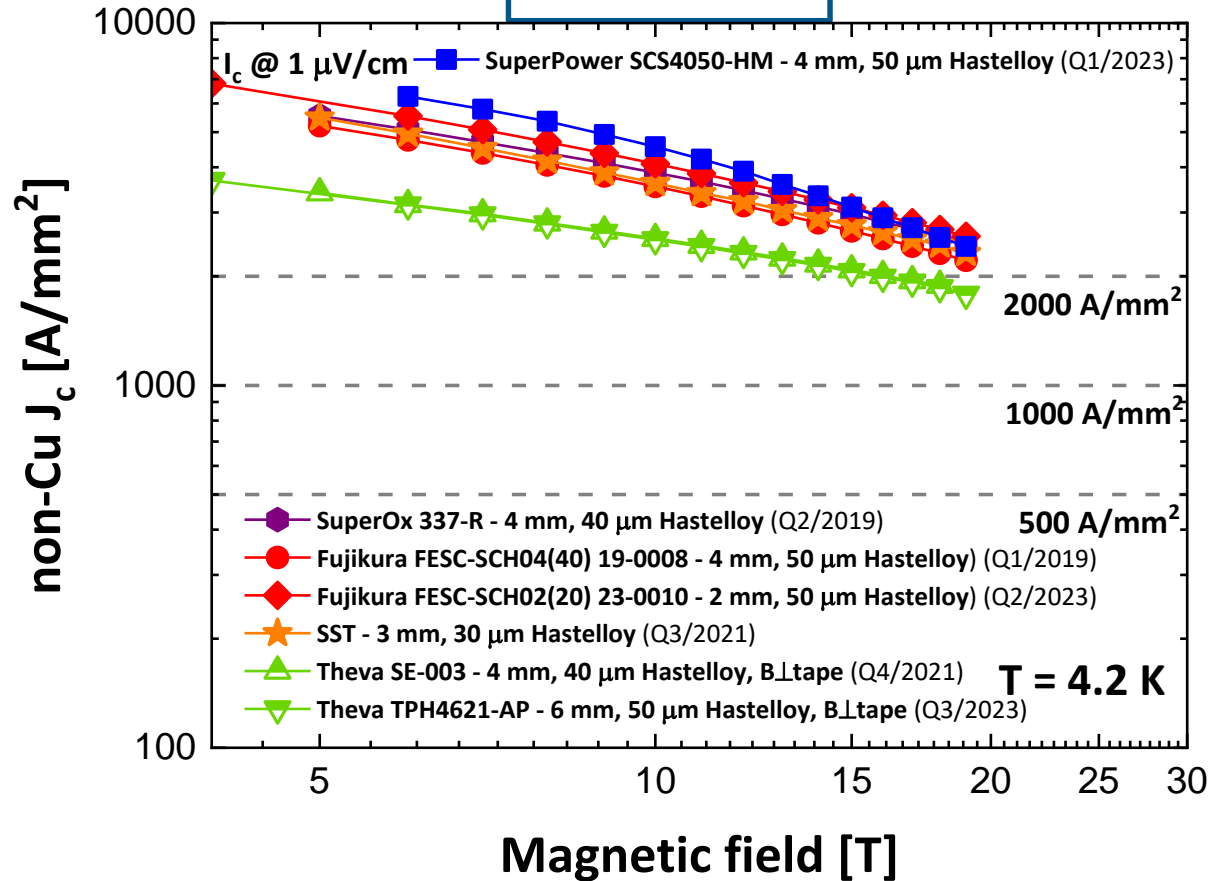


Comparison of the performance: non-Cu J_c

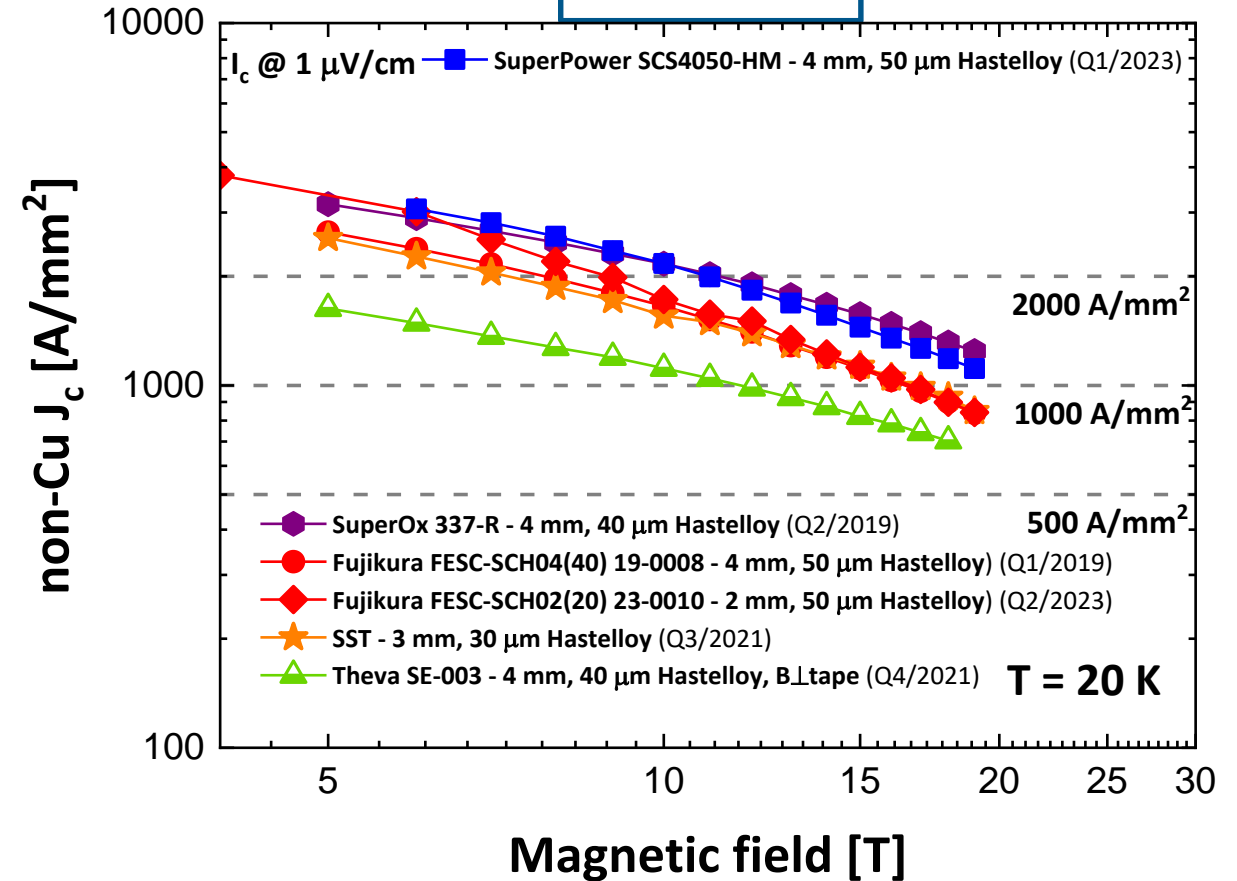
The non-Cu J_c corresponds to the critical current divided by the tape cross-section area minus the Cu area

$$\text{non-Cu } J_c = \frac{I_c}{A_{\text{tot}} - A_{\text{Cu}}}$$

T = 4.2 K

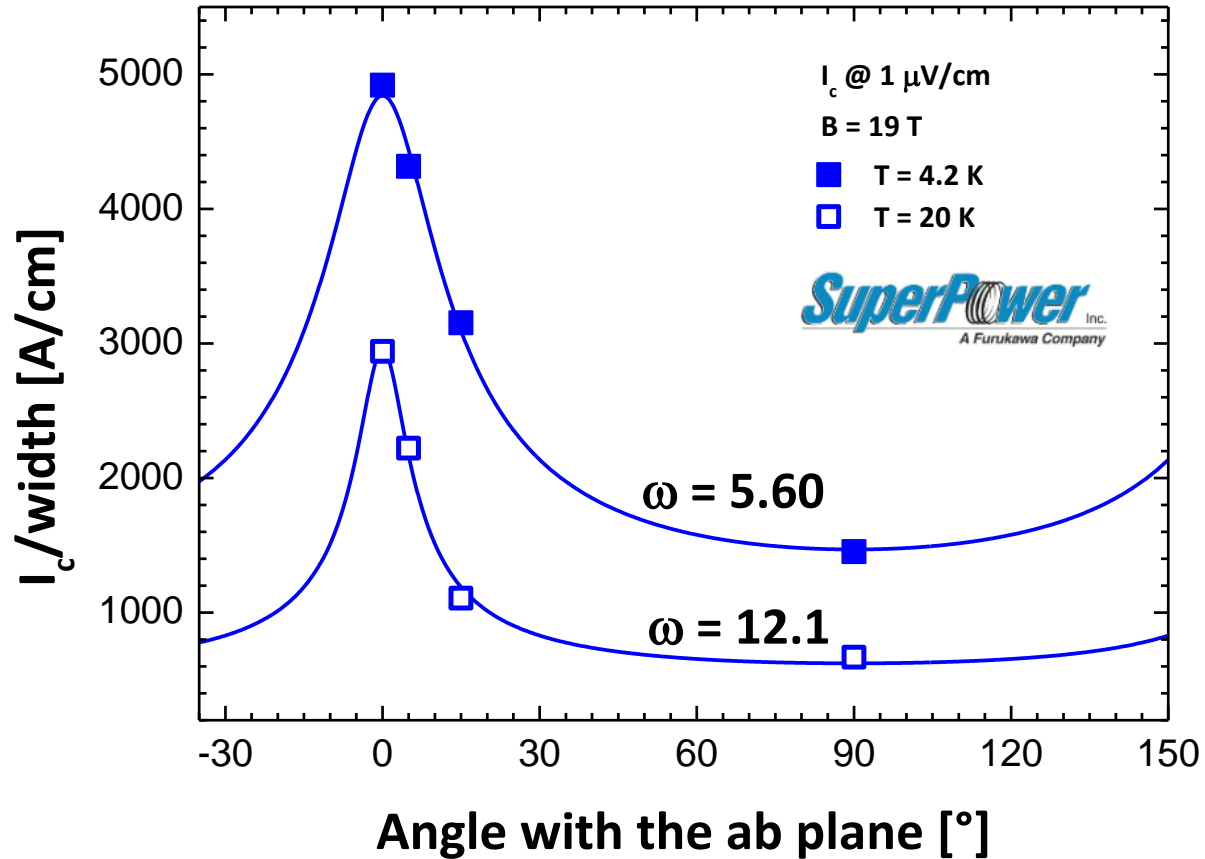


T = 20 K

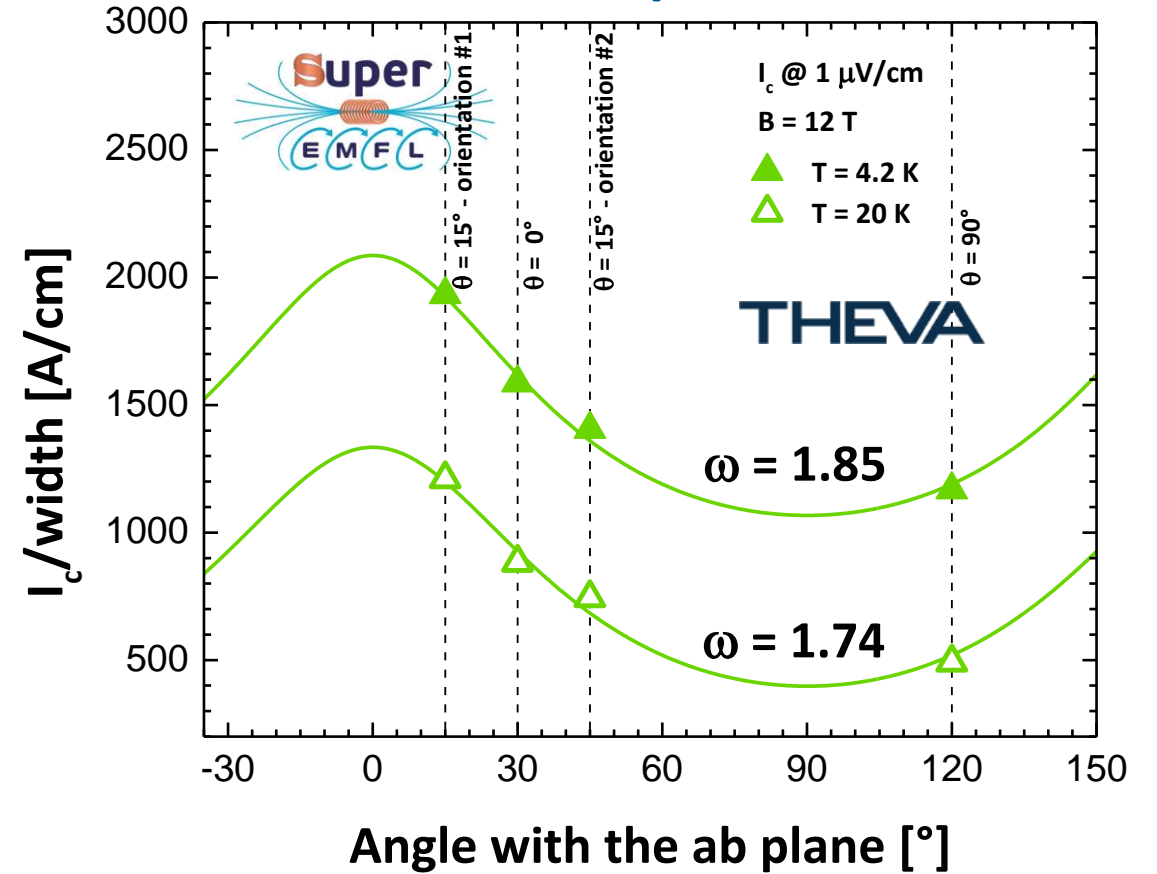


Angular dependence of I_c : two examples

Without artificial nanocolumns – Q1/2023



With artificial nanoparticles – Q4/2021



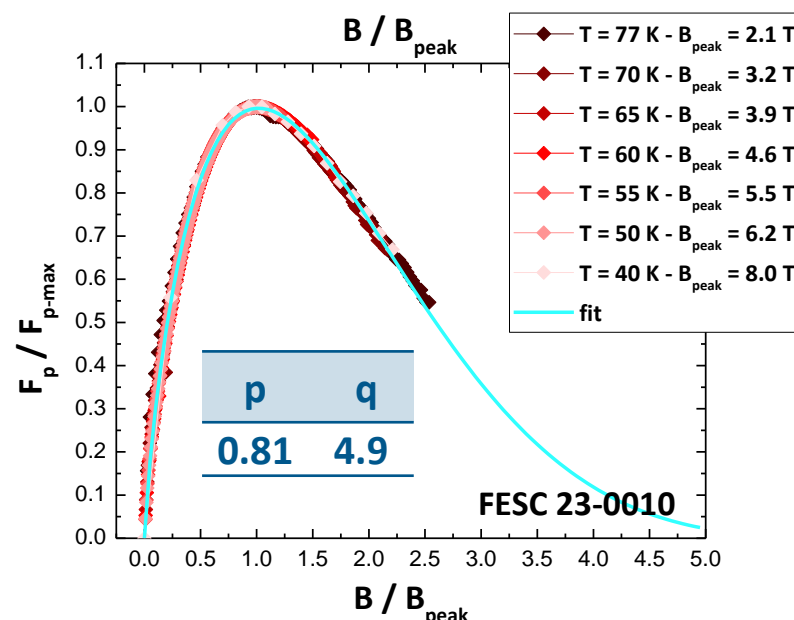
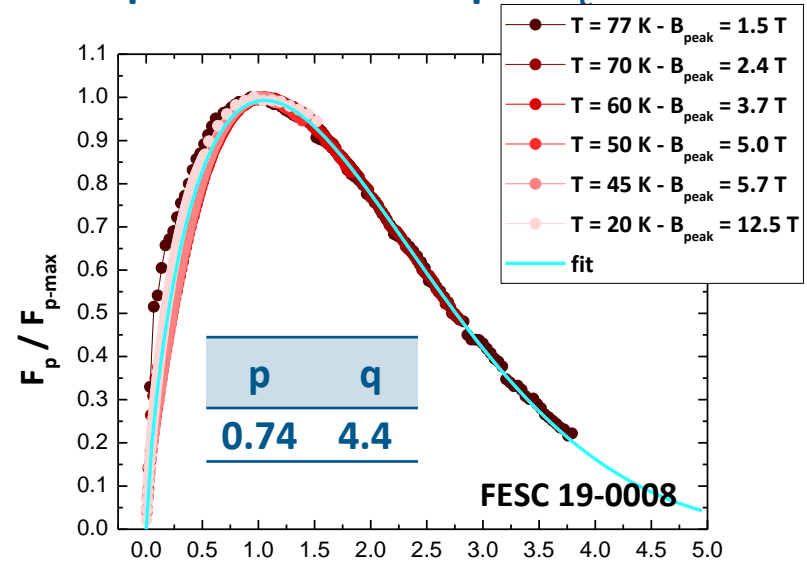
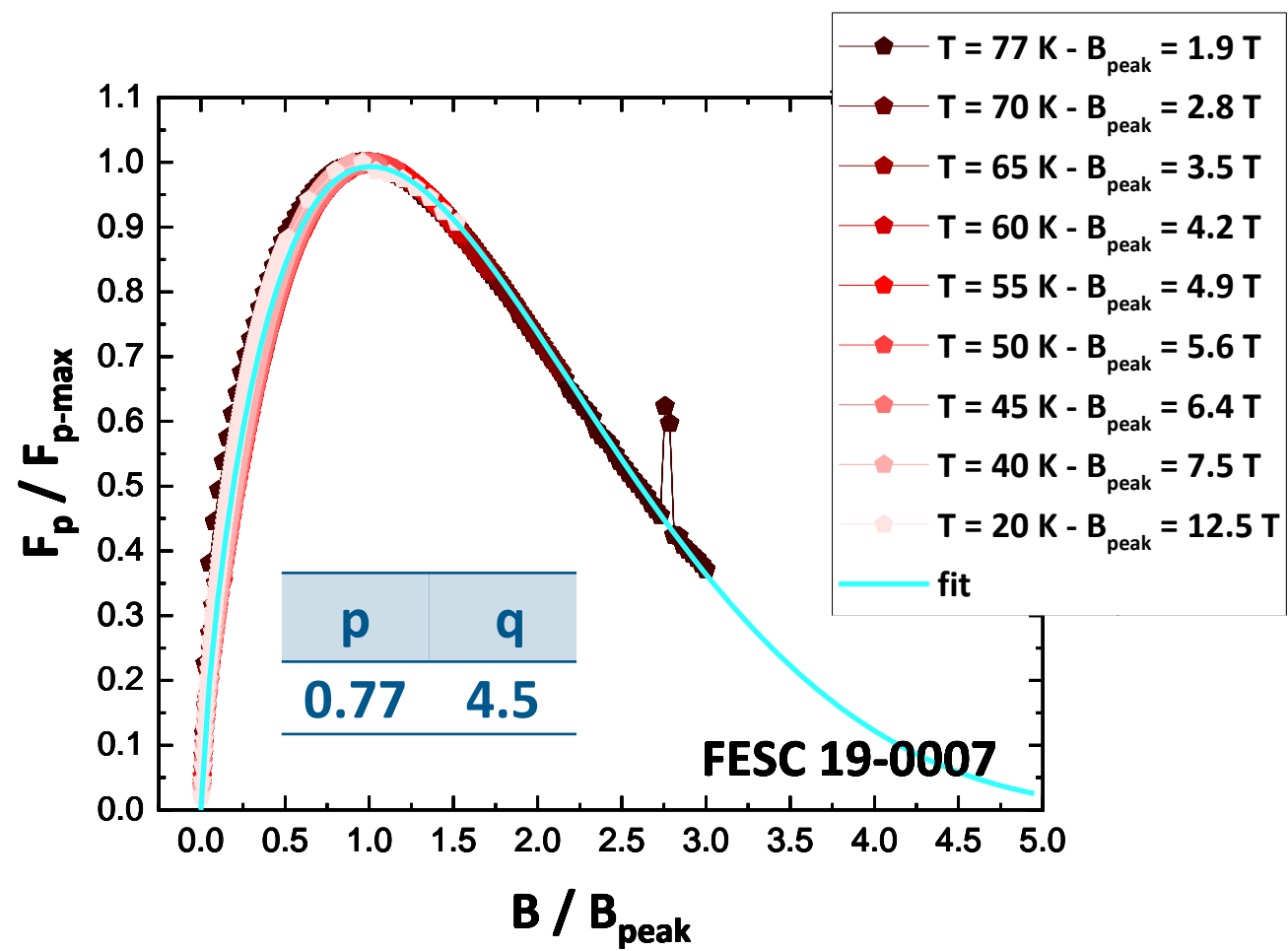
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Fujikura tapes: Pinning force scaling

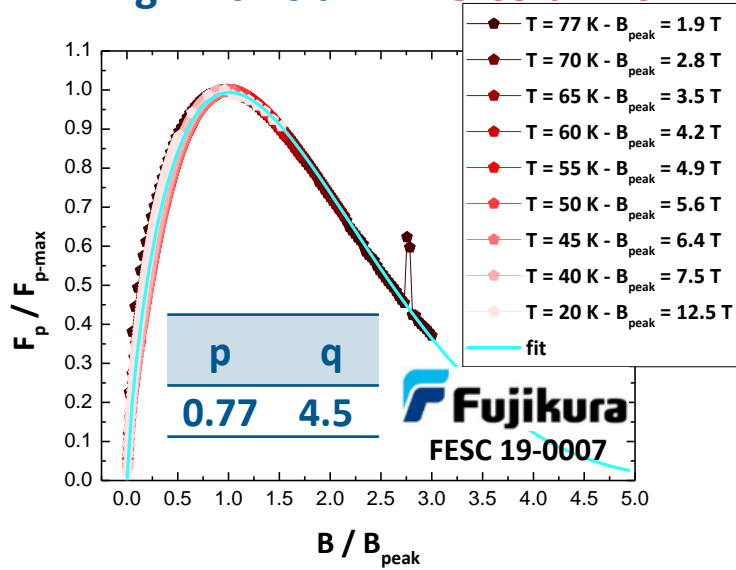
Normalized pinning force vs B / B_{peak} , from $M(B)$ curves up to 7 T with some points from transport I_c



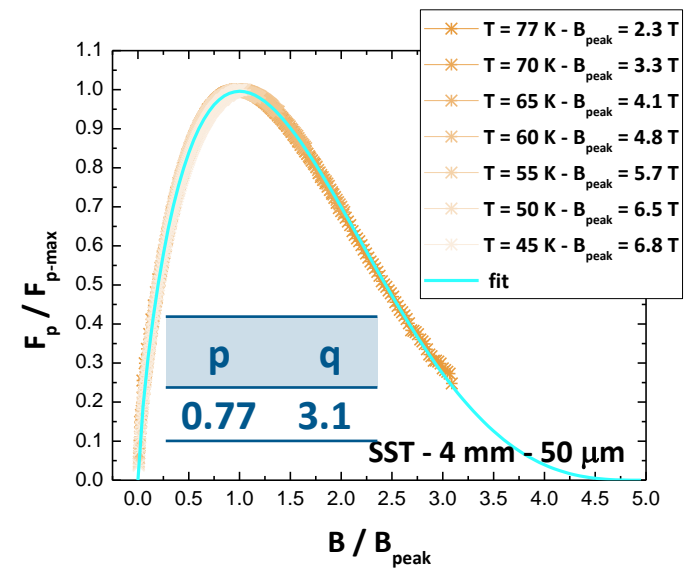
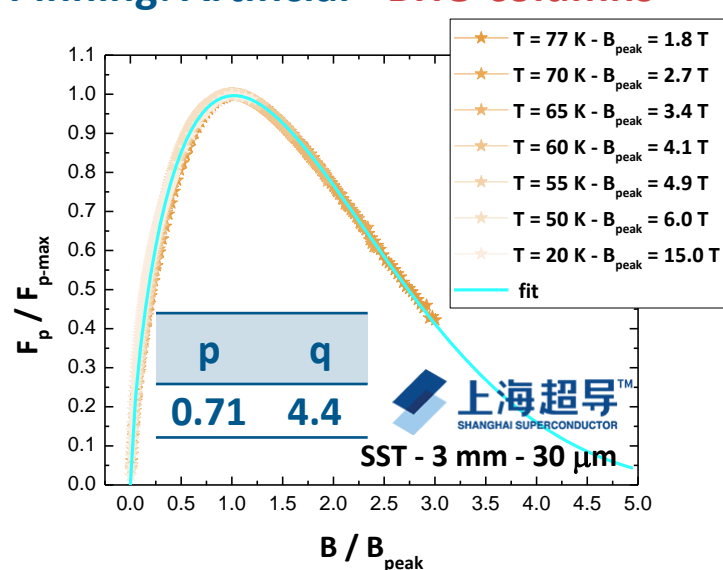
Concatenated fit of the type $f_p \propto b^p (1-b)^q$

Pinning force scaling, $B \perp$ tape: Comparison

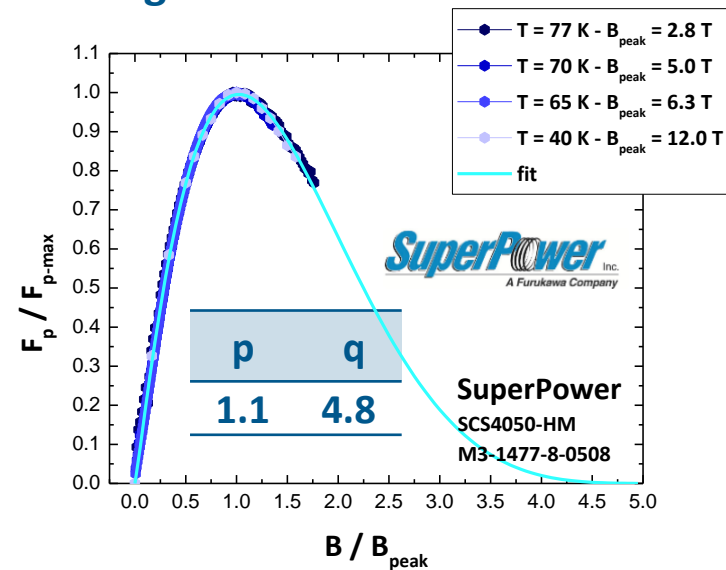
Pinning: Artificial - BHO columns



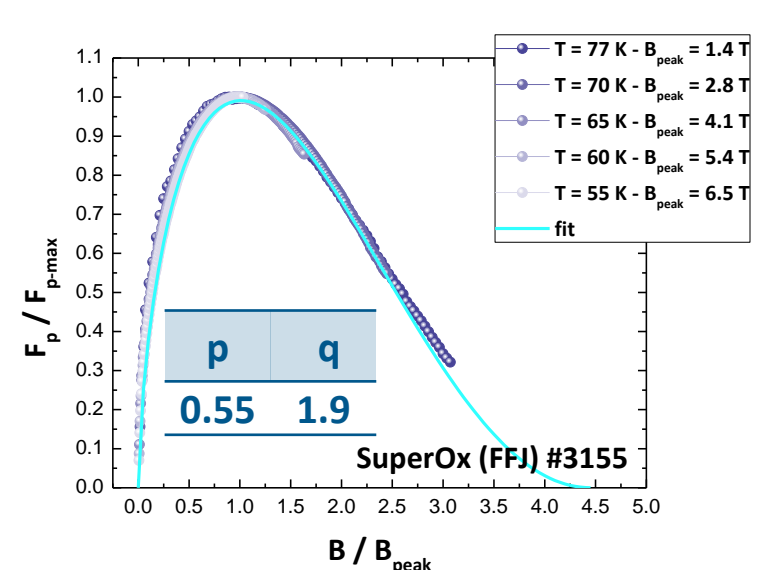
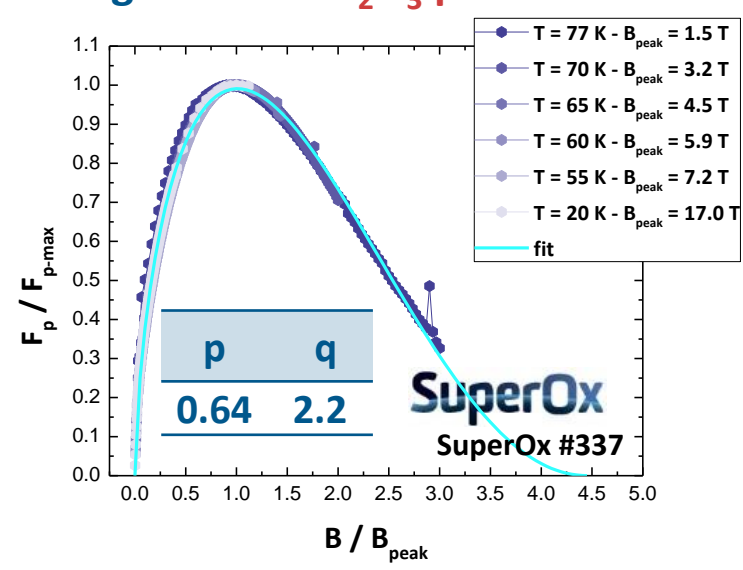
Pinning: Artificial - BHO columns



Pinning: Artificial - BZO columns



Pinning: Native - Y_2O_3 particles

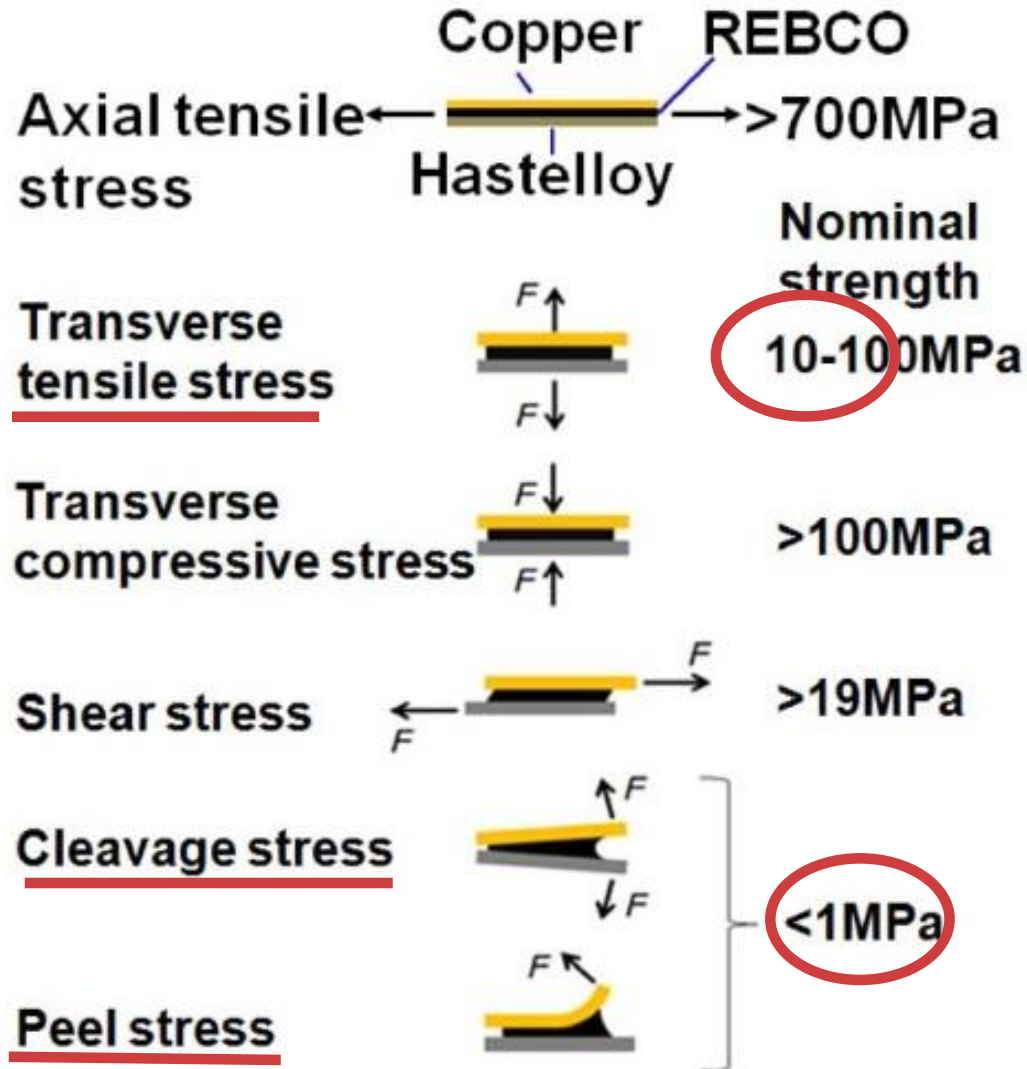


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- Results of the measurement campaign on REBCO coated conductors from various manufacturers
 - Main characteristics of the examined tapes
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- **A new experiment to test the delamination strength of REBCO coated conductors**
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High in-field J_c is not sufficient for UHF magnets

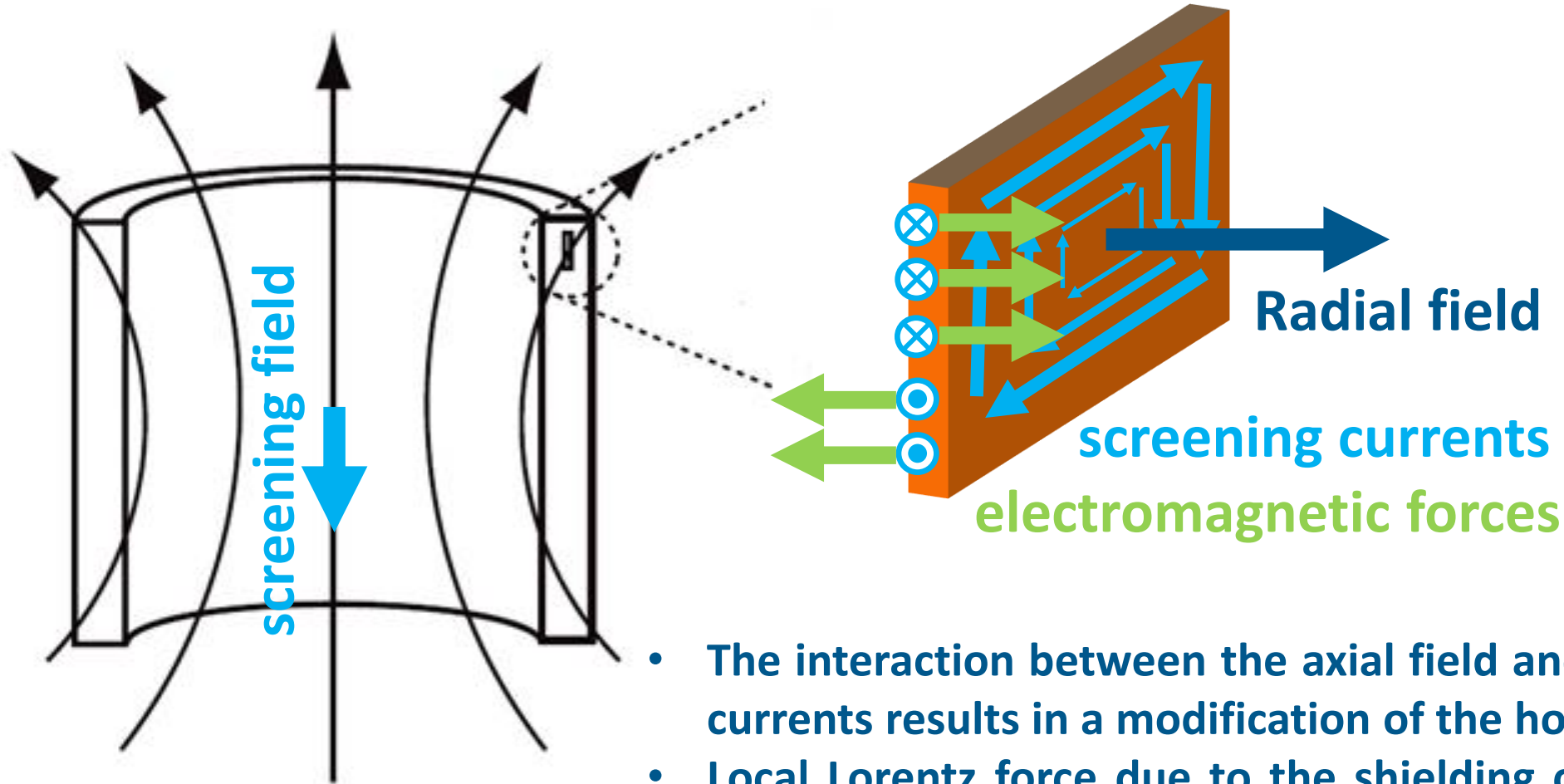
A short note on the mechanical properties



- REBCO tapes are inherently prone to delamination
- Adhesion between layers seems to be process dependent
- A standardized process to determine the properties of the tapes is missing

High in-field J_c is not sufficient for UHF magnets

Conductor degradation/delamination due the screening currents

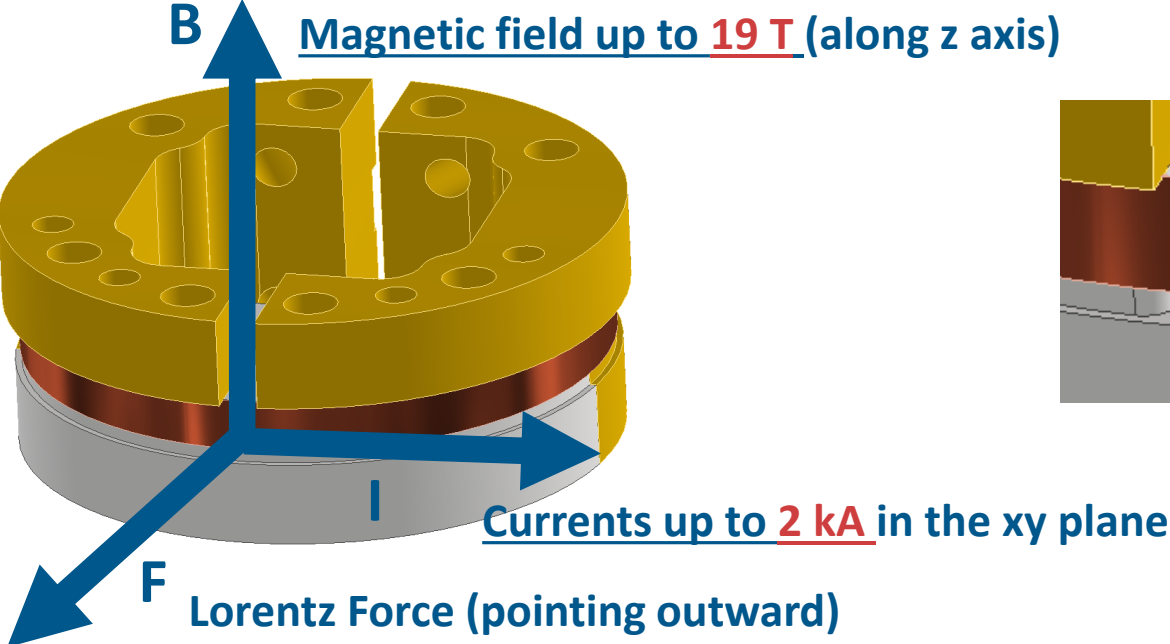


- The interaction between the axial field and the screening currents results in a modification of the hoop stress
- Local Lorentz force due to the shielding currents can be source of delamination force

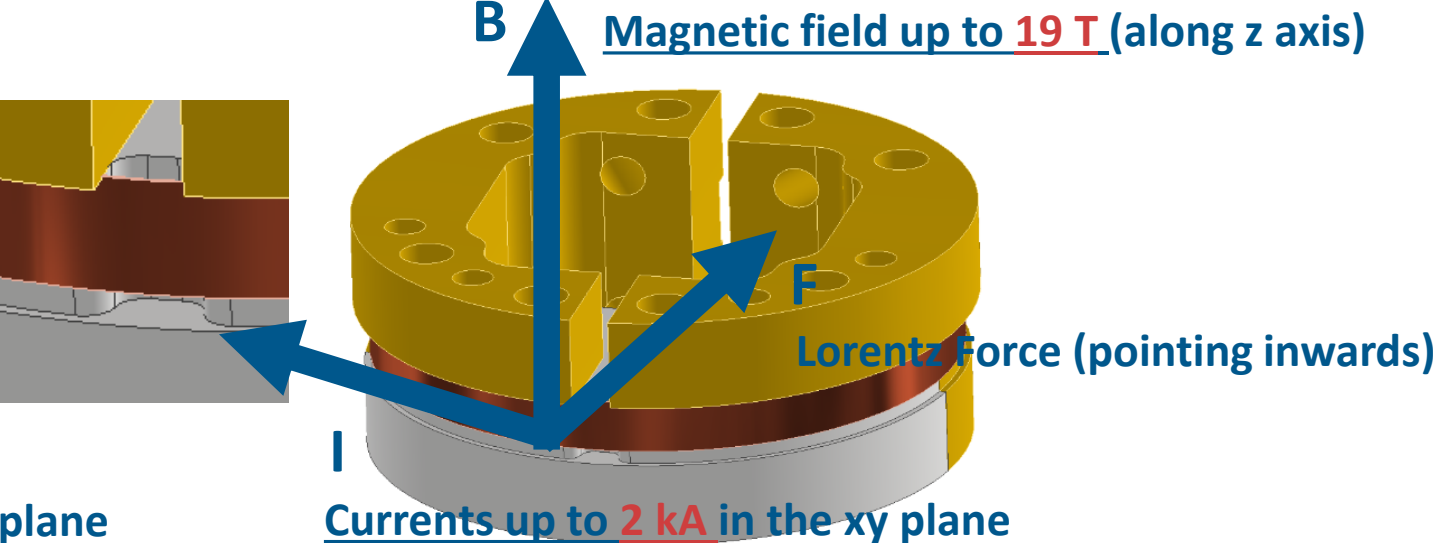
Delamination strength measurements under I x B force

A novel experiment for a direct measurement of the conductor degradation

REBCO layer on the outside

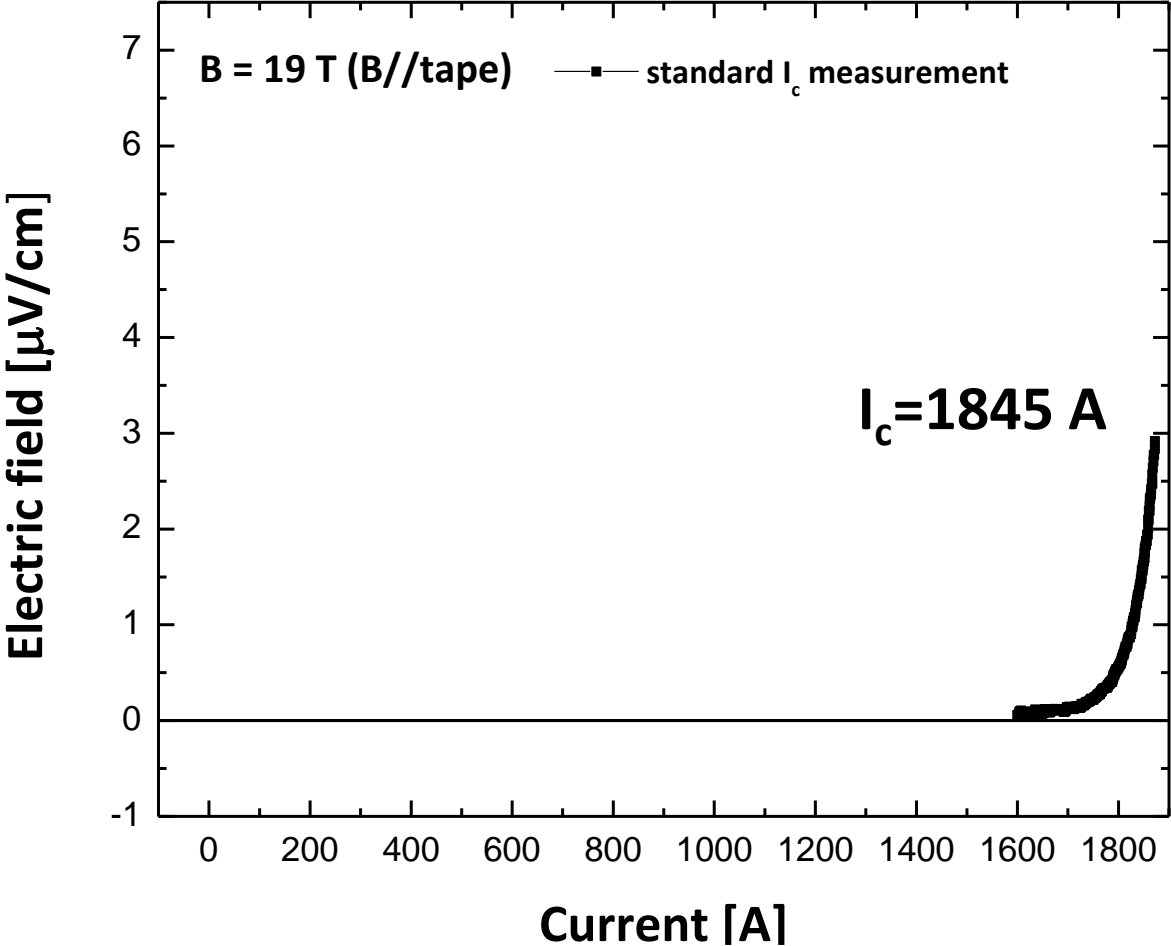


REBCO layer on the inside

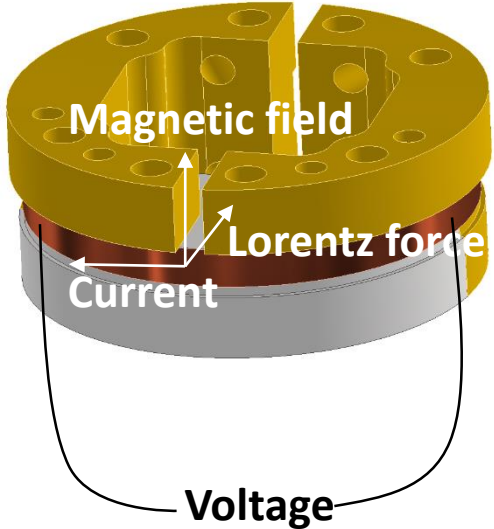


The average stress due to the Lorentz force is $\bar{\sigma}_T = \frac{F_R}{S} = \frac{I B}{w}$

Results of the experiment #1 on Fujikura FESC SCH04

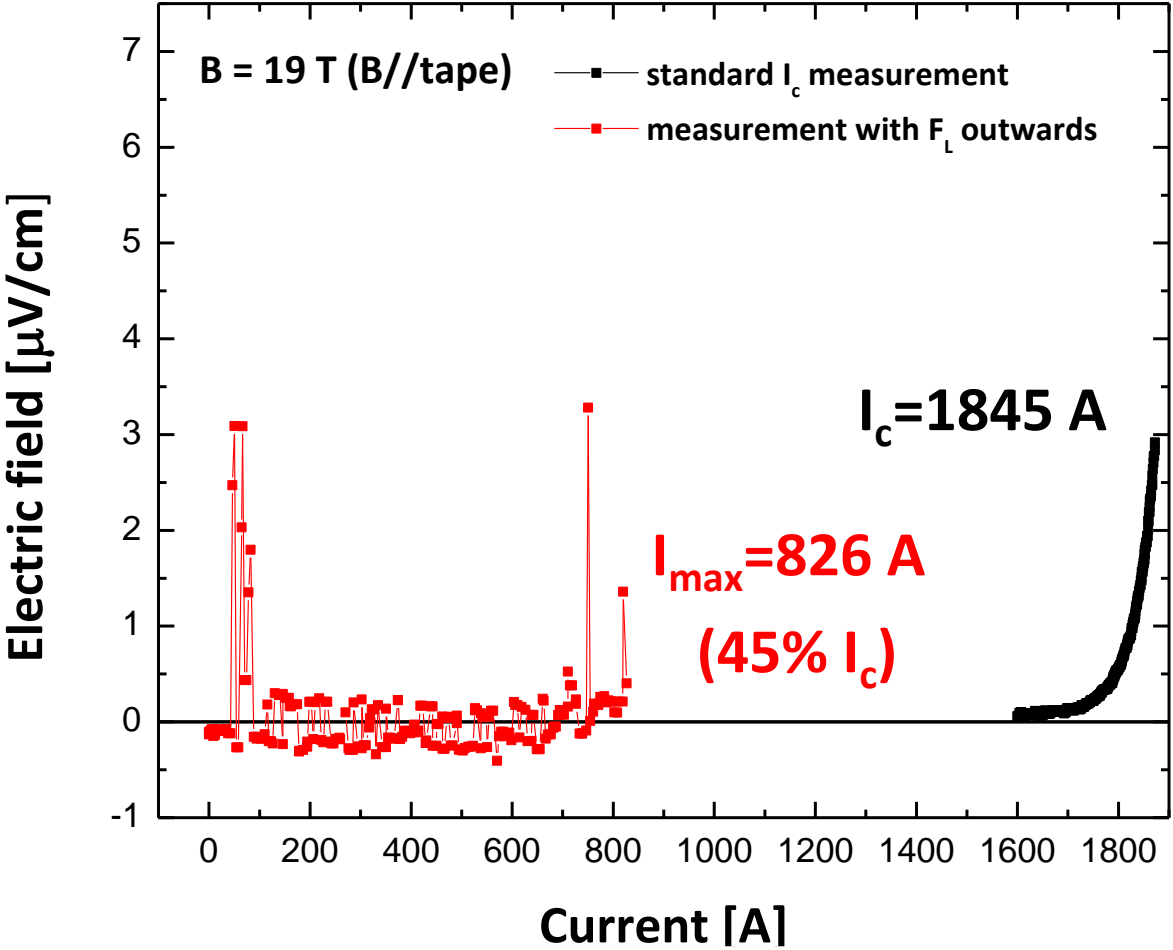


Reference I_c measurement
Force inwards
REBCO layer inside



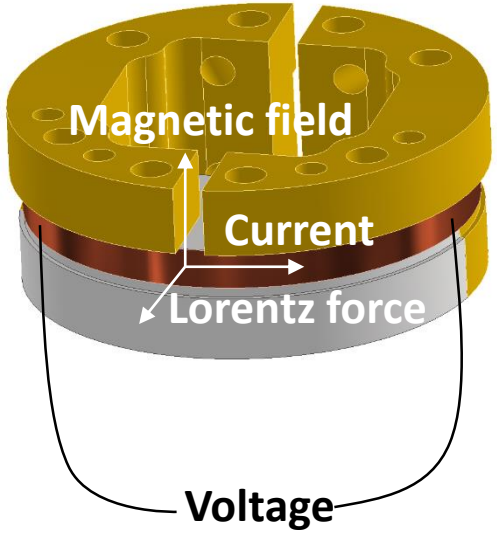
Quench protection threshold $\sim 10 \mu\Omega/\text{cm}$

Results of the experiment #1 on Fujikura FESC SCH04



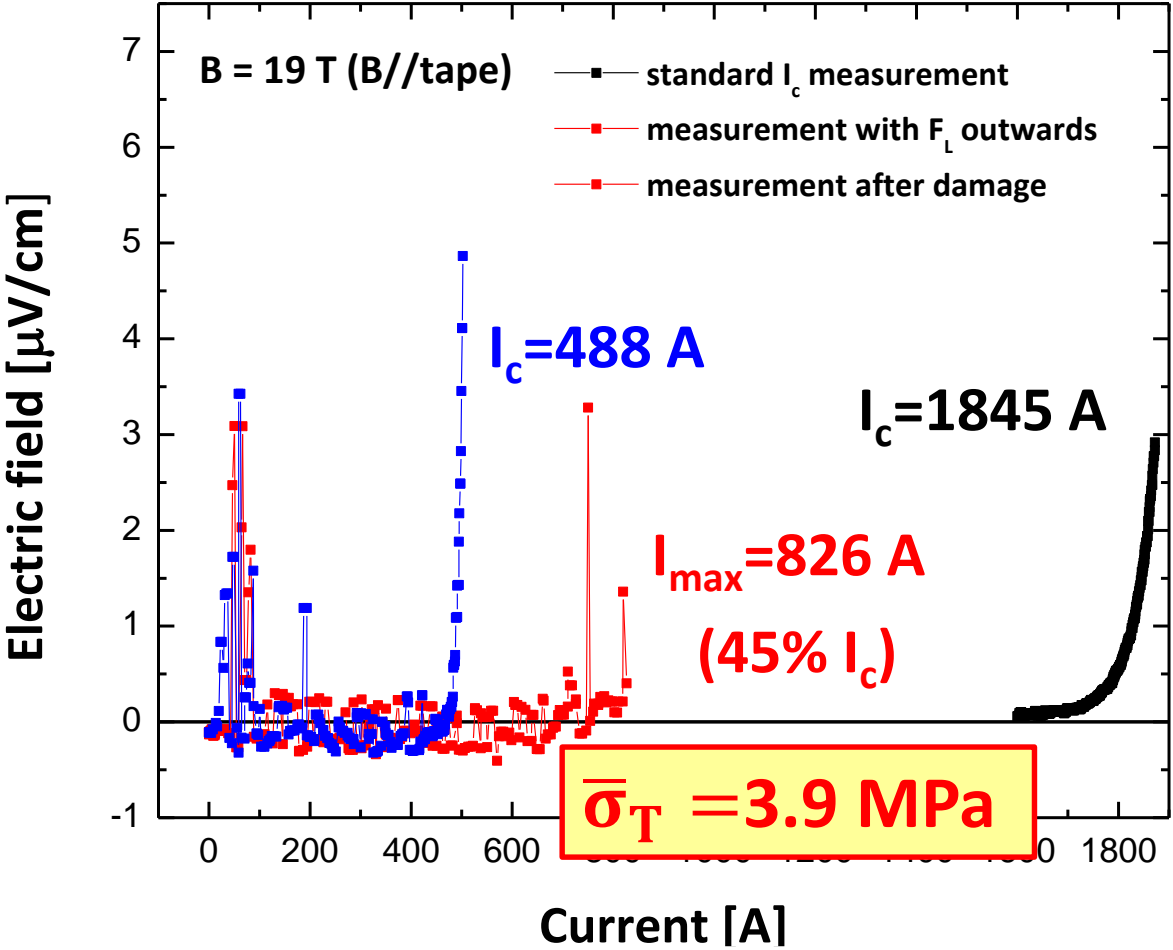
Delamination test - configuration #1

Force outwards
REBCO layer outside

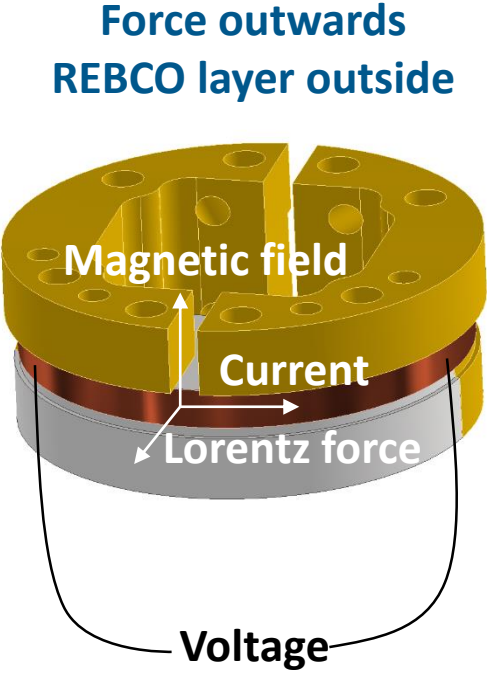


Quench protection threshold $\sim 10 \mu\Omega/cm$

Results of the experiment #1 on Fujikura FESC SCH04



Delamination test - configuration #1



Quench protection threshold $\sim 10 \mu\Omega/\text{cm}$

What has been tested so far



Type: **FESC SCH04**
Tape ID: 19-0008

Delamination strength ~ **4 MPa**
(45% I_c)

$\bar{\sigma}_T = 3.9$ MPa F_L outward
 $\bar{\sigma}_T = 4.1$ MPa F_L inward



Type: **FESC SCH02**
Tape ID: 23-0010

Delamination strength ~ **4.3 MPa**
(39% I_c)

$\bar{\sigma}_T = 4.3$ MPa F_L inward



Type: **SCS4050-AP**
Tape ID: M3-1464-7

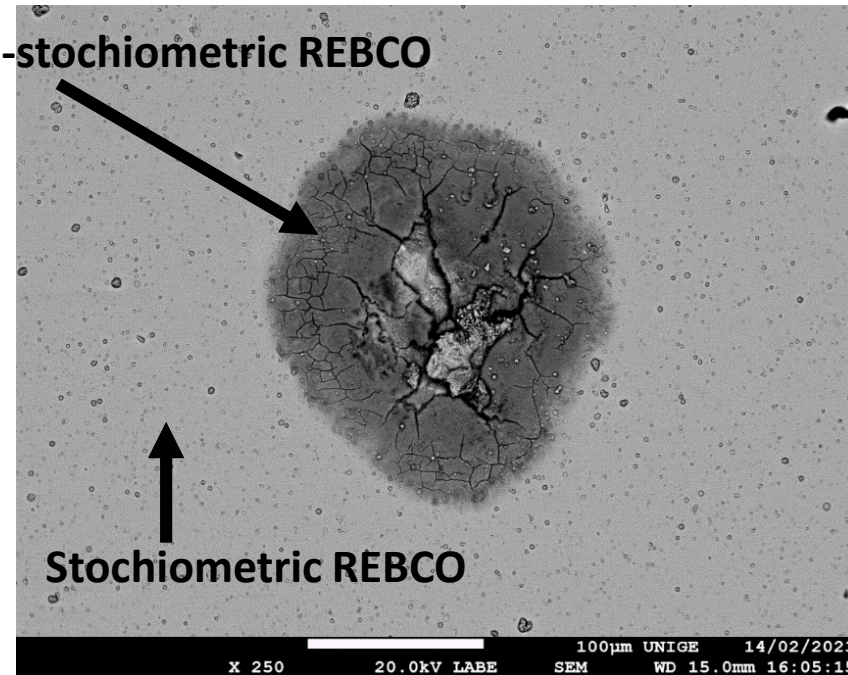
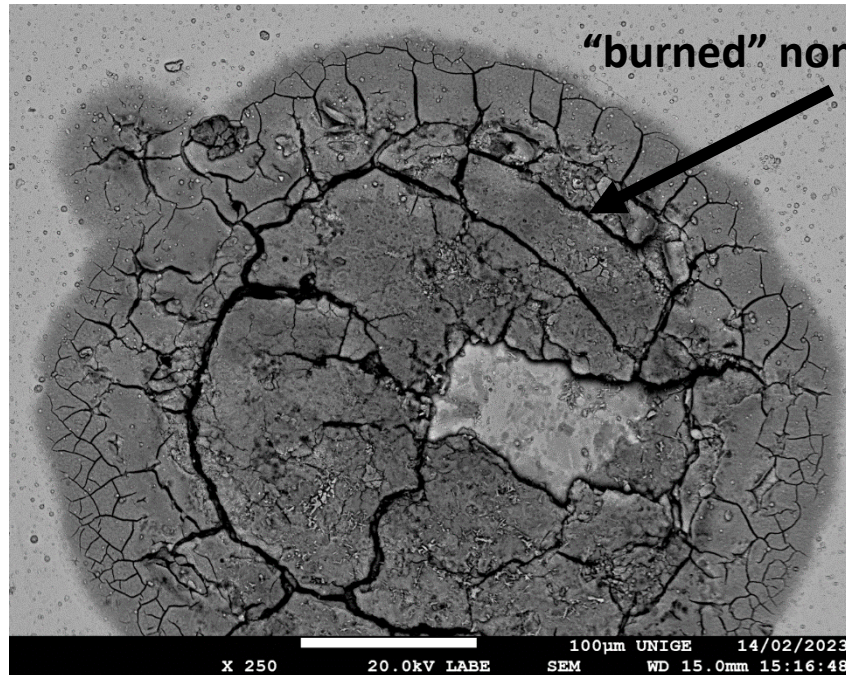
Delamination strength ~ **5.5 MPa**
(82% I_c)

$\bar{\sigma}_T = 5.5$ MPa F_L inward

Delamination strength and forensic microscopy

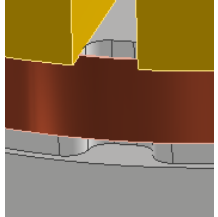
SEM-EDX and 3D Optical microscopy

Delamination → Quench → Local heating → Blistering

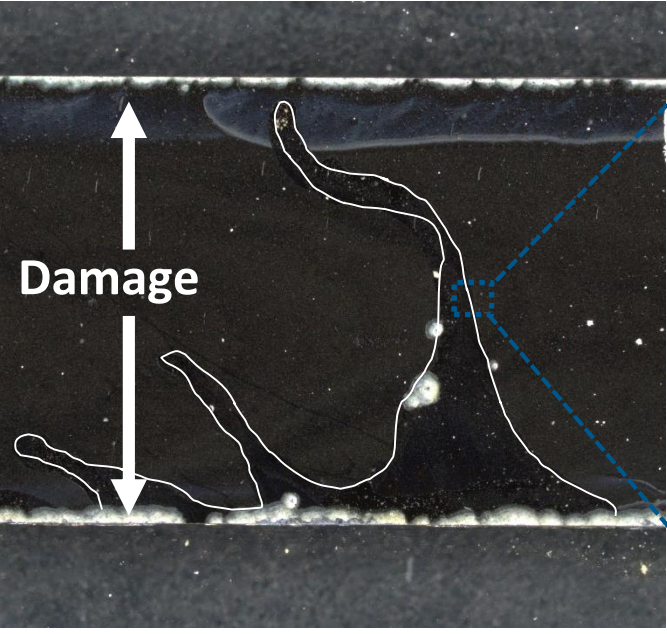


Delamination strength and forensic microscopy

SEM-EDX and 3D Optical microscopy



Evidence of delaminated area where the tape was not supported



3D optical microscope analysis



z-axis
color
code

97% of I_c was lost after the delamination experiment

What has been tested so far



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Tape ID: 19-0008

Delamination strength ~ **4 MPa**
(45% I_c)

$\bar{\sigma}_T = 3.9$ MPa F_L outward
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Longitudinal damage on both
edges of the CC + Blisters



Type: FESC SCH02
Tape ID: 23-0010

Delamination strength ~ **4.3 MPa**
(39% I_c)

$\bar{\sigma}_T = 4.3$ MPa F_L inward

Longitudinal damage on both
edges of the CC + Blisters



Type: SCS4050-AP
Tape ID: M3-1464-7

Delamination strength ~ **5.5 MPa**
(82% I_c)

$\bar{\sigma}_T = 5.5$ MPa F_L inward

Longitudinal damage on 1 edge
of the CC + Blisters



Conclusions

The performance gap at low temperatures, high fields between various manufacturers is relatively small in spite of the differences in process, composition and pinning landscape

Magnet designers need high performance tapes but also **high fidelity $I_c(B,\theta,T)$ characterization**. However, it is difficult to produce complete datasets

The **new experiment** to measure the **delamination strength** of REBCO tapes aims to produce **robust data with a reproducible process**. The ongoing activities involve:

- Systematic study about the role of the CC edges on the delamination strength (Laser vs mechanical slitting; Slitting on 1 or 2 edges)
- FEM study in collaboration with CERN to determine the local stress distribution in our experiment
- Correlation between visual damage (optical microscopy) and local I_c values from magnetic scans

Thank you for the attention !

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